

## Double channel high-side driver with analog current sense for 24 V automotive applications


**PowerSSO-24**

### Features

Description	Parameter	Value
Max. transient supply voltage	$V_{CC}$	58 V
Operating voltage range	$V_{CC}$	8 to 36 V
Typ. on-state resistance (per channel)	$R_{ON}$	50 m $\Omega$
Current limitation (typ.)	$I_{LIM}$	34 A
Off-state supply current	$I_S$	2 $\mu$ A



- AEC-Q100 qualified
- General
  - Very low standby current
  - 3.0 V CMOS compatible input
  - Optimized electromagnetic emission
  - Very low electromagnetic susceptibility
  - Compliant with European directive 2002/95/EC
  - Fault reset standby pin (FR\_Stby)
- Diagnostic functions
  - Proportional load current sense
  - High current sense precision for wide range currents
  - Off-state openload detection
  - Output short to  $V_{CC}$  detection
  - Overload and short to ground latch-off
  - Thermal shutdown latch-off
  - Very low current sense leakage
- Protections
  - Undervoltage shutdown
  - Overvoltage clamp
  - Load current limitation
  - Self limiting of fast thermal transients
  - Protection against loss of ground and loss of  $V_{CC}$
  - Thermal shutdown
  - Electrostatic discharge protection

#### Product status link

[VND5T050AK-E](#)

#### Product summary

Order code	VND5T050AK-E
Package	PowerSSO-24
Packing	Tube
Order code	VND5T050AKTR-E
Package	PowerSSO-24
Packing	Tape and reel

### Applications

- All types of resistive, inductive and capacitive loads

## Description

The VND5T050AK-E is a monolithic device made using STMicroelectronics VIPower technology, intended for driving resistive or inductive loads with one side connected to the ground. Active  $V_{CC}$  pin voltage clamp protects the device against low energy spikes.

The device integrates an analog current sense, which delivers a current proportional to the load current.

Fault conditions such as overload, overtemperature, or short to  $V_{CC}$  are reported via the current sense pin.

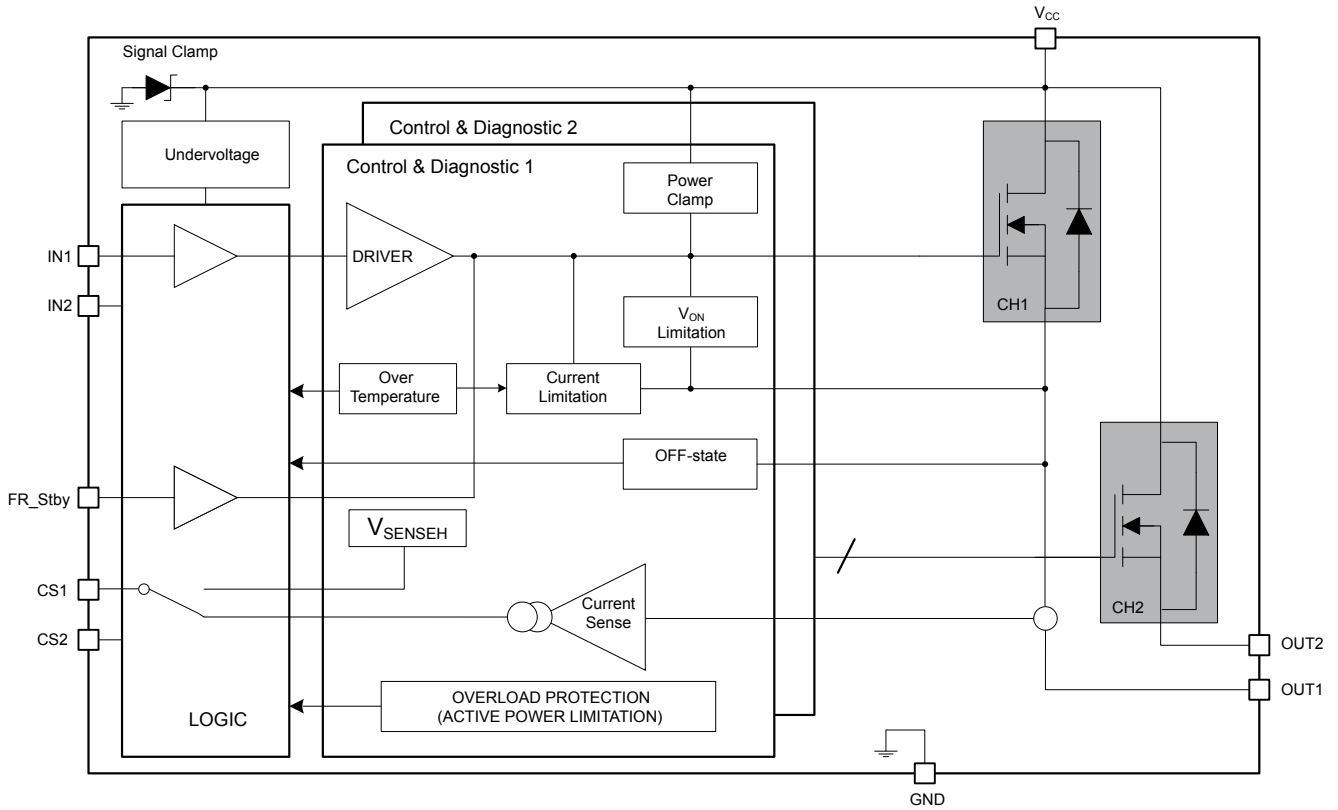
Output current limitation protects the device in overload conditions. The device latches off in case of overload or thermal shutdown.

The device is reset by a low level pass on the fault reset standby pin.

A permanent low level on the inputs and on the fault reset standby pins disables all outputs and sets the device in standby mode.

# 1 Block diagram and pin description

Figure 1. Block diagram

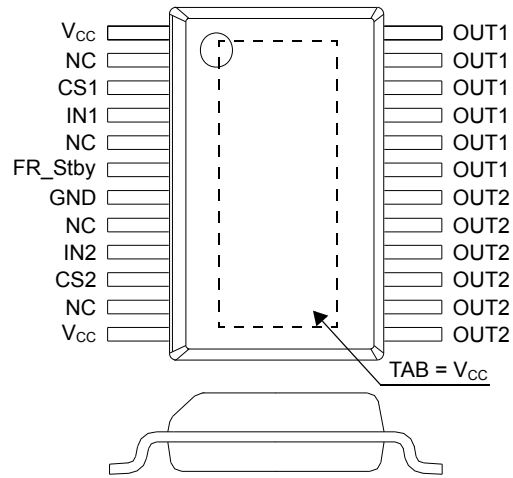


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Table 1. Pin function

Name	Function
V <sub>CC</sub>	Battery connection.
OUT1, 2	Power outputs.
GND	Ground connection.
IN1, 2	Voltage controlled input pins with hysteresis, CMOS compatible. They control output switch state.
CS1, 2	Analog current sense pins, they deliver a current proportional to the load current.
FR_Stby	In case of latch-off for overtemperature/overcurrent condition, a low pulse on the FR_Stby pin is needed to reset the channel. The device enters in standby mode if all inputs and the FR_Stby pin are low.

Figure 2. Configuration diagram PowerSSO-24 (top view)



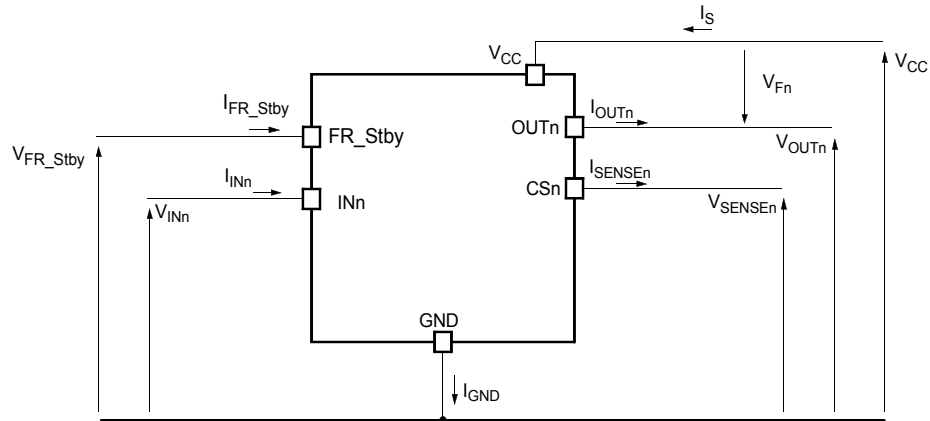
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Table 2. Suggested connections for unused and not connected pins

Connection/pin	CurrentSense	NC	Output	Input	FR_Stby
Floating	Not allowed	X <sup>(1)</sup>	X	X	X
To ground	Through 10 kΩ resistor	X	Not allowed	Through 10 kΩ resistor	Through 10 kΩ resistor

1. X: do not care.

## 2 Electrical specification

**Figure 3. Current and voltage conventions**


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### 2.1 Absolute maximum ratings

Stressing the device above the ratings listed in the [Table 3](#) may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those indicated in the operating sections of this specification is not implied. Exposure to the conditions reported in this section for extended periods may affect device reliability.

**Table 3. Absolute maximum ratings**

Symbol	Parameter	Value	Unit	
$V_{CC}$	DC supply voltage	58	V	
$-V_{CC}$	Reverse DC supply voltage	0.3	V	
$-I_{GND}$	DC reverse ground pin current	200	mA	
$I_{OUT}$	DC output current	Internally limited	A	
$-I_{OUT}$	Reverse DC output current	30	A	
$I_{IN}$	DC input current	-1 to 10	mA	
$I_{FR\_Stby}$	Fault reset standby DC input current	-1 to 1.5	mA	
$-I_{CSENSE}$	DC reverse CS pin current	200	mA	
$V_{CSENSE}$	Current sense maximum voltage	$(V_{CC} - 58)$ to $V_{CC}$	V	
$E_{MAX}$	Maximum switching energy ( $L = 50$ mH; $V_{BAT} = 32$ V; $T_{Jstart} = 150$ °C; $I_{OUT} = 2$ A)	210	mJ	
$L_{smax}$	Maximum stray inductance in short circuit condition $R_L = 300$ mΩ, $V_{BAT} = 32$ V, $T_{Jstart} = 150$ °C, $I_{OUT} = I_{limH}$ (max.)	40	μH	
$V_{ESD}$	Electrostatic discharge (human body model: $R = 1.5$ kΩ, $C = 100$ pF)	IN1, 2	4000	V
		CS1, 2	2000	
		FR_Stby	4000	
		OUT1, 2	5000	
		$V_{CC}$	5000	
$V_{ESD}$	Charge device model (CDM-AEC-Q100-011)	750	V	

Symbol	Parameter	Value	Unit
$T_J$	Junction operating temperature	-40 to 150	°C
$T_{stg}$	Storage temperature	-55 to 150	°C

## 2.2 Thermal data

**Table 4. Thermal data**

Symbol	Parameter	Value	Unit
$R_{thJC}$	Thermal resistance, junction-to-case (with one channel ON)	2.4	°C/W
$R_{thJA}$	Thermal resistance, junction-to-ambient	See Figure 27	°C/W

## 2.3 Electrical characteristics

8 V <  $V_{CC}$  < 36 V, -40 °C <  $T_J$  < 150 °C, unless otherwise specified.

**Table 5. Power section**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{CC}$	Operating supply voltage		8	24	36	V
$V_{USD}$	Undervoltage shutdown			3.5	5	V
$V_{USDhyst}$	Undervoltage shutdown hysteresis			0.5		V
$R_{ON}$	On-state resistance <sup>(1)</sup>	$I_{OUT} = 2\text{ A}$ , $T_J = 25\text{ °C}$		50		mΩ
		$I_{OUT} = 2\text{ A}$ , $T_J = 150\text{ °C}$			100	
$V_{clamp}$	Clamp voltage	$I_S = 20\text{ mA}$	58	64	70	V
$I_S$	Supply current	Off-state, $V_{CC} = 24\text{ V}$ , $T_J = 25\text{ °C}$ , $V_{IN} = V_{OUT} = V_{SENSE} = 0\text{ V}$ , $V_{FR\_Stby} = 0\text{ V}$		2 <sup>(2)</sup>	5 <sup>(2)</sup>	μA
		On-state, $V_{CC} = 24\text{ V}$ , $V_{IN} = 5\text{ V}$ , $I_{OUT} = 0\text{ A}$		4.2	6	mA
$I_{L(off)}$	Off-state output current	$V_{IN} = V_{OUT} = 0\text{ V}$ , $V_{CC} = 24\text{ V}$ , $T_J = 25\text{ °C}$	0	0.01	3	μA
		$V_{IN} = V_{OUT} = 0\text{ V}$ , $V_{CC} = 24\text{ V}$ , $T_J = 125\text{ °C}$	0		5	
$V_F$	Output - $V_{CC}$ diode voltage	$-I_{OUT} = 2\text{ A}$ , $T_J = 150\text{ °C}$			0.7	V

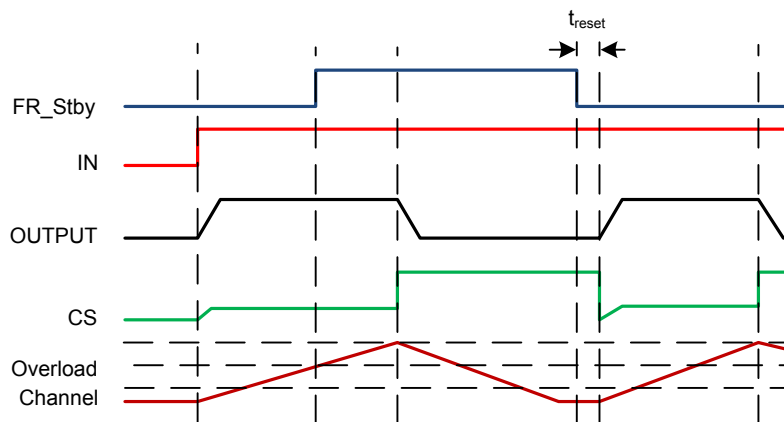
1. For each channel.
2. Power MOSFET leakage included.

**Table 6. Switching ( $V_{CC} = 24\text{ V}$ ,  $T_J = 25\text{ °C}$ )**

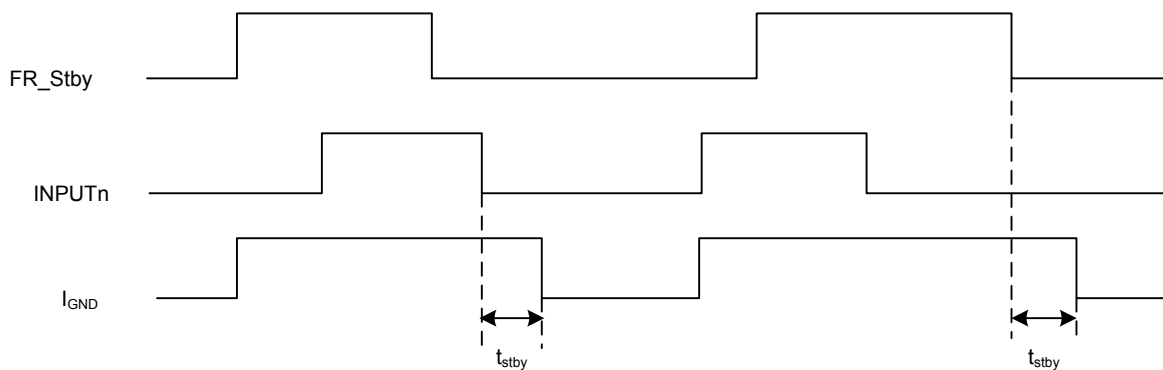
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$R_L = 12\ \Omega$		30		$\mu\text{s}$
$t_{d(off)}$	Turn-off delay time	$R_L = 12\ \Omega$		40		$\mu\text{s}$
$(dV_{OUT}/dt)_{(on)}$	Turn-on voltage slope	$R_L = 12\ \Omega$		0.7		$\text{V}/\mu\text{s}$
$(dV_{OUT}/dt)_{(off)}$	Turn-off voltage slope	$R_L = 12\ \Omega$		0.8		$\text{V}/\mu\text{s}$
$W_{ON}$	Switching energy losses during $t_{won}$	$R_L = 12\ \Omega$		0.5		mJ
$W_{OFF}$	Switching energy losses during $t_{woff}$	$R_L = 12\ \Omega$		0.3		mJ

**Table 7. Logic inputs**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{IL}$	Input low level voltage				0.9	V
$I_{IL}$	Low level input current	$V_{IN} = 0.9\text{ V}$	1			$\mu\text{A}$
$V_{IH}$	Input high level voltage		2.1			V
$I_{IH}$	High level input current	$V_{IN} = 2.1\text{ V}$			10	$\mu\text{A}$
$V_{I(hyst)}$	Input hysteresis voltage		0.25			V
$V_{ICL}$	Input clamp voltage	$I_{IN} = 1\text{ mA}$	5.5		7	V
		$I_{IN} = -1\text{ mA}$		-0.7		V
$V_{FR\_Stby\_L}$	Fault_reset_standby low level voltage				0.9	V
$I_{FR\_Stby\_L}$	Low level fault_reset_standby current	$V_{FR\_Stby} = 0.9\text{ V}$	1			$\mu\text{A}$
$V_{FR\_Stby\_H}$	Fault_reset_standby high level voltage		2.1			V
$I_{FR\_Stby\_H}$	High level fault_reset_standby current	$V_{FR\_Stby} = 2.1\text{ V}$			10	$\mu\text{A}$
$V_{FR\_Stby(hyst)}$	Fault_reset_standby hysteresis voltage		0.25			V
$V_{FR\_Stby\_CL}$	Fault_reset_standby clamp voltage	$I_{FR\_Stby} = 15\text{ mA}$ ( $t < 10\text{ ms}$ )	11		15	V
		$I_{FR\_Stby} = -1\text{ mA}$		-0.7		V
$t_{reset}$	Overload latch-off reset time	See <a href="#">Figure 4</a>	2		24	$\mu\text{s}$
$t_{stby}$	Standby delay	See <a href="#">Figure 5</a>	120		1200	$\mu\text{s}$

**Figure 4.  $t_{\text{reset}}$  definition**


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**Figure 5.  $t_{\text{stby}}$  definition**


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**Table 8. Protections and diagnostics**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{\text{limH}}$	DC short circuit current	$V_{\text{CC}} = 24 \text{ V}$	24	34	46	A
		$5 \text{ V} < V_{\text{CC}} < 36 \text{ V}$			46	
$I_{\text{limL}}$	Short circuit current during thermal cycling	$V_{\text{CC}} = 24 \text{ V}, T_{\text{R}} < T_{\text{J}} < T_{\text{TSD}}$		8.5		A
$T_{\text{TSD}}$	Shutdown temperature		150	175	200	$^{\circ}\text{C}$
$T_{\text{R}}$	Reset temperature		$T_{\text{RS}} + 1$	$T_{\text{RS}} + 5$		$^{\circ}\text{C}$
$T_{\text{RS}}$	Thermal reset of status		135			$^{\circ}\text{C}$
$T_{\text{HYST}}$	Thermal hysteresis ( $T_{\text{TSD}} - T_{\text{R}}$ )			7		$^{\circ}\text{C}$
$V_{\text{DEMAG}}$	Turn-off output voltage clamp	$I_{\text{OUT}} = 2 \text{ A}, V_{\text{IN}} = 0 \text{ V}, L = 6 \text{ mH}$	$V_{\text{CC}} - 58$	$V_{\text{CC}} - 64$	$V_{\text{CC}} - 70$	V
$V_{\text{ON}}$	Output voltage drop limitation	$I_{\text{OUT}} = 100 \text{ mA}, T_{\text{J}} = -40 \text{ }^{\circ}\text{C} \text{ to } 150 \text{ }^{\circ}\text{C}$		25		mV



**Table 9. Current sense (8 V < V<sub>CC</sub> < 36 V)**

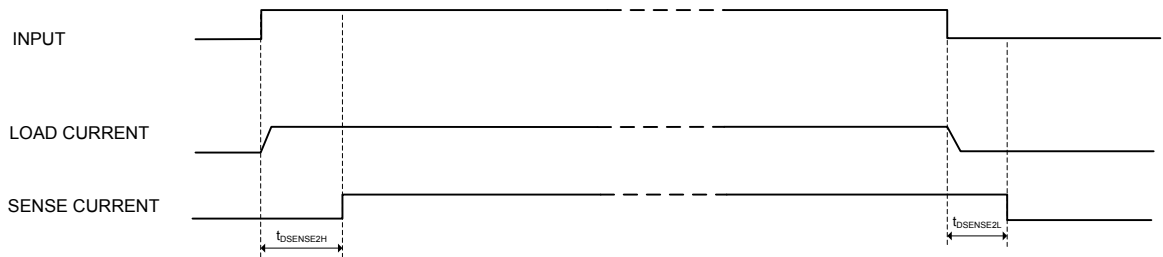
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
K <sub>OL</sub>	I <sub>OUT</sub> /I <sub>SENSE</sub>	I <sub>OUT</sub> = 10 mA, V <sub>SENSE</sub> = 0.5 V, T <sub>J</sub> = -40 °C to 150 °C	564	2800	5563	
		I <sub>OUT</sub> = 10 mA, V <sub>SENSE</sub> = 0.5 V, T <sub>J</sub> = 25 °C to 150 °C	972		4895	
K <sub>LED</sub>	I <sub>OUT</sub> /I <sub>SENSE</sub>	I <sub>OUT</sub> = 50 mA, V <sub>SENSE</sub> = 0.5 V, T <sub>J</sub> = -40 °C to 150 °C	1193	2650	4268	
		I <sub>OUT</sub> = 50 mA, V <sub>SENSE</sub> = 0.5 V, T <sub>J</sub> = 25 °C to 150 °C	1416		3958	
dK <sub>LED</sub> /K <sub>LEDTOT</sub> <sup>(1)</sup>	Current sense ratio drift	I <sub>OUT</sub> = 12 mA to 60 mA, I <sub>CAL</sub> = 35 mA, V <sub>SENSE</sub> = 0.5 V	-35		35	%
K <sub>0</sub>	I <sub>OUT</sub> /I <sub>SENSE</sub>	I <sub>OUT</sub> = 100 mA, V <sub>SENSE</sub> = 0.5 V, T <sub>J</sub> = -40 °C to 150 °C	1409	2540	3726	
dK <sub>0</sub> /K <sub>0</sub> <sup>(1)</sup>	Current sense ratio drift	I <sub>OUT</sub> = 100 mA, V <sub>SENSE</sub> = 0.5 V, T <sub>J</sub> = -40 °C to 150 °C	-20		20	%
K <sub>1</sub>	I <sub>OUT</sub> /I <sub>SENSE</sub>	I <sub>OUT</sub> = 0.7 A, V <sub>SENSE</sub> = 2 V, T <sub>J</sub> = -40 °C to 150 °C	1597	2190	2764	
dK <sub>1</sub> /K <sub>1</sub> <sup>(1)</sup>	Current sense ratio drift	I <sub>OUT</sub> = 0.7 A, V <sub>SENSE</sub> = 2 V, T <sub>J</sub> = -40 °C to 150 °C	-15		15	%
K <sub>2</sub>	I <sub>OUT</sub> /I <sub>SENSE</sub>	I <sub>OUT</sub> = 2 A, V <sub>SENSE</sub> = 2 V, T <sub>J</sub> = -40 °C to 150 °C	1850	2190	2550	
dK <sub>2</sub> /K <sub>2</sub> <sup>(1)</sup>	Current sense ratio drift	I <sub>OUT</sub> = 2 A, V <sub>SENSE</sub> = 2 V, T <sub>J</sub> = -40 °C to 150 °C	-10		10	%
K <sub>3</sub>	I <sub>OUT</sub> /I <sub>SENSE</sub>	I <sub>OUT</sub> = 8 A, V <sub>SENSE</sub> = 4 V, T <sub>J</sub> = -40 °C to 150 °C	2050	2190	2280	
dK <sub>3</sub> /K <sub>3</sub> <sup>(1)</sup>	Current sense ratio drift	I <sub>OUT</sub> = 8 A, V <sub>SENSE</sub> = 4 V, T <sub>J</sub> = -40 °C to 150 °C	-3		3	%
I <sub>SENSE0</sub>	Analog sense leakage current	I <sub>OUT</sub> = 0 A, V <sub>SENSE</sub> = 0 V, V <sub>IN</sub> = 0 V, T <sub>J</sub> = -40 °C to 150 °C	0		1	μA
		I <sub>OUT</sub> = 0 A, V <sub>SENSE</sub> = 0 V, V <sub>IN</sub> = 5 V, T <sub>J</sub> = -40 °C to 150 °C	0		2	
V <sub>SENSE</sub>	Max analog sense output voltage	I <sub>OUT</sub> = 8 A, R <sub>SENSE</sub> = 3.9 kΩ	5			V
V <sub>SENSEH</sub>	Analog sense output voltage in fault condition <sup>(2)</sup>	V <sub>CC</sub> = 24 V, R <sub>SENSE</sub> = 3.9 kΩ	7.5	8.5	9.5	V
I <sub>SENSEH</sub>	Analog sense output current in fault condition <sup>(2)</sup>	V <sub>CC</sub> = 24 V, V <sub>SENSE</sub> = 5 V	4.9	7	12	mA
t <sub>DSSENSE2H</sub>	Delay response time from rising edge of INPUT pins	V <sub>SENSE</sub> < 4 V, 0.15 A < I <sub>OUT</sub> < 8 A, I <sub>SENSE</sub> = 90% of I <sub>SENSEMAX</sub> , (see Figure 6)		150	300	μs
Δt <sub>DSSENSE2H</sub>	Delay response time between rising edge of output current and rising edge of current sense	V <sub>SENSE</sub> < 4 V, I <sub>SENSE</sub> = 90% of I <sub>SENSEMAX</sub> , I <sub>OUT</sub> = 90% of I <sub>OUTMAX</sub> , I <sub>OUTMAX</sub> = 2 A (see Figure 10)			250	μs

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{\text{DSENSE2L}}$	Delay response time from falling edge of INPUT pins	$V_{\text{SENSE}} < 4 \text{ V}$ , $0.15 \text{ A} < I_{\text{OUT}} < 8 \text{ A}$ , $I_{\text{SENSE}} = 10\% \text{ of } I_{\text{SENSEMAX}}$ (see Figure 6)		5	20	$\mu\text{s}$

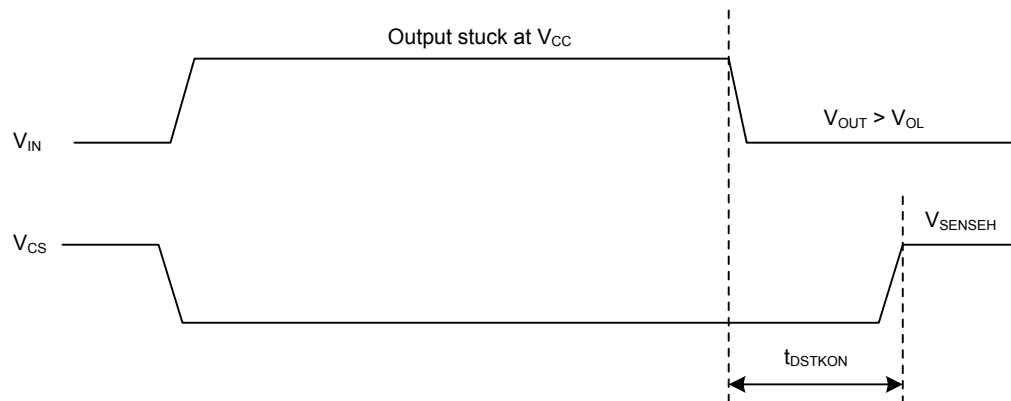
1. Specified by design, not tested in production.
2. Fault condition includes: power limitation, overtemperature and openload in off-state condition.

**Table 10. Openload detection ( $V_{\text{FR\_Stby}} = 5 \text{ V}$ )**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{\text{OL}}$	Openload off-state voltage detection threshold	$V_{\text{IN}} = 0 \text{ V}$ , $8 \text{ V} < V_{\text{CC}} < 36 \text{ V}$	2	-	4	V
$t_{\text{DSTKON}}$	Output short circuit to VCC detection delay at turn off	See Figure 7	180	-	1800	$\mu\text{s}$
$I_{\text{L(off2)}}$	Off-state output current at $V_{\text{OUT}} = 4 \text{ V}$	$V_{\text{IN}} = 0 \text{ V}$ , $V_{\text{SENSE}} = 0 \text{ V}$ , $V_{\text{OUT}}$ rising from $0 \text{ V}$ to $4 \text{ V}$	-120	-	0	$\mu\text{A}$
$t_{\text{d\_vol}}$	Delay response from output rising edge to $V_{\text{SENSE}}$ rising edge in openload	$V_{\text{OUT}} = 4 \text{ V}$ , $V_{\text{IN}} = 0 \text{ V}$ , $V_{\text{SENSE}} = 90\% \text{ of } V_{\text{SENSEH}}$ , $R_{\text{SENSE}} = 3.9 \text{ k}\Omega$		-	20	$\mu\text{s}$
$t_{\text{DFRSTK\_ON}}$	Output short circuit to VCC detection delay at FR_Stby activation	Input1, 2 = low (see Figure 9)		-	50	$\mu\text{s}$

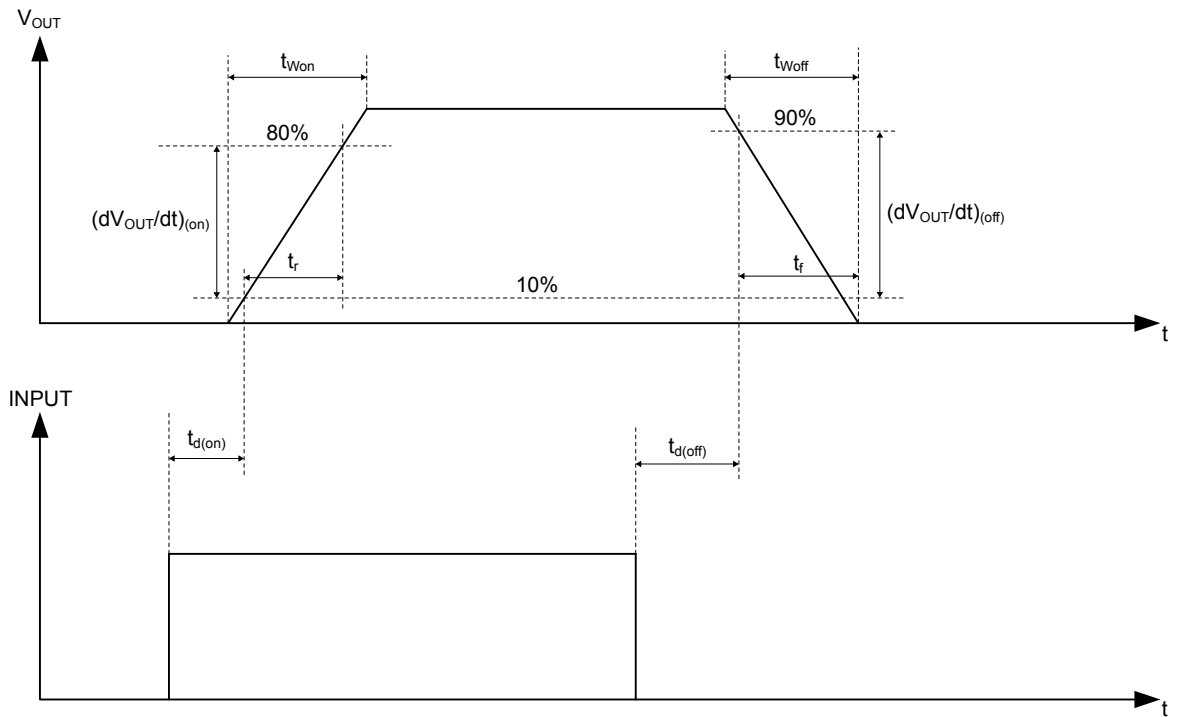
**Figure 6. Current sense delay characteristics**


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**Figure 7. Openload off-state delay timing**

 NOTE:  $V_{\text{FR\_stby}} = 5 \text{ V}$ .

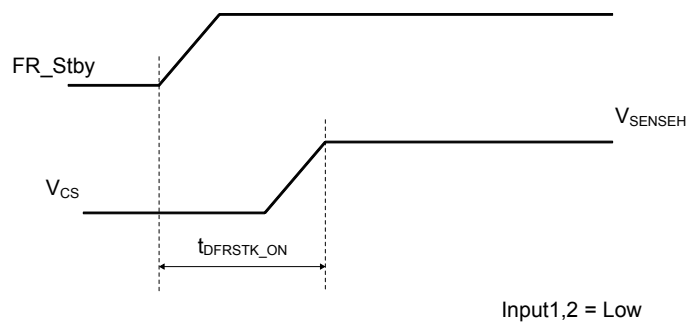
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Figure 8. Switching characteristics



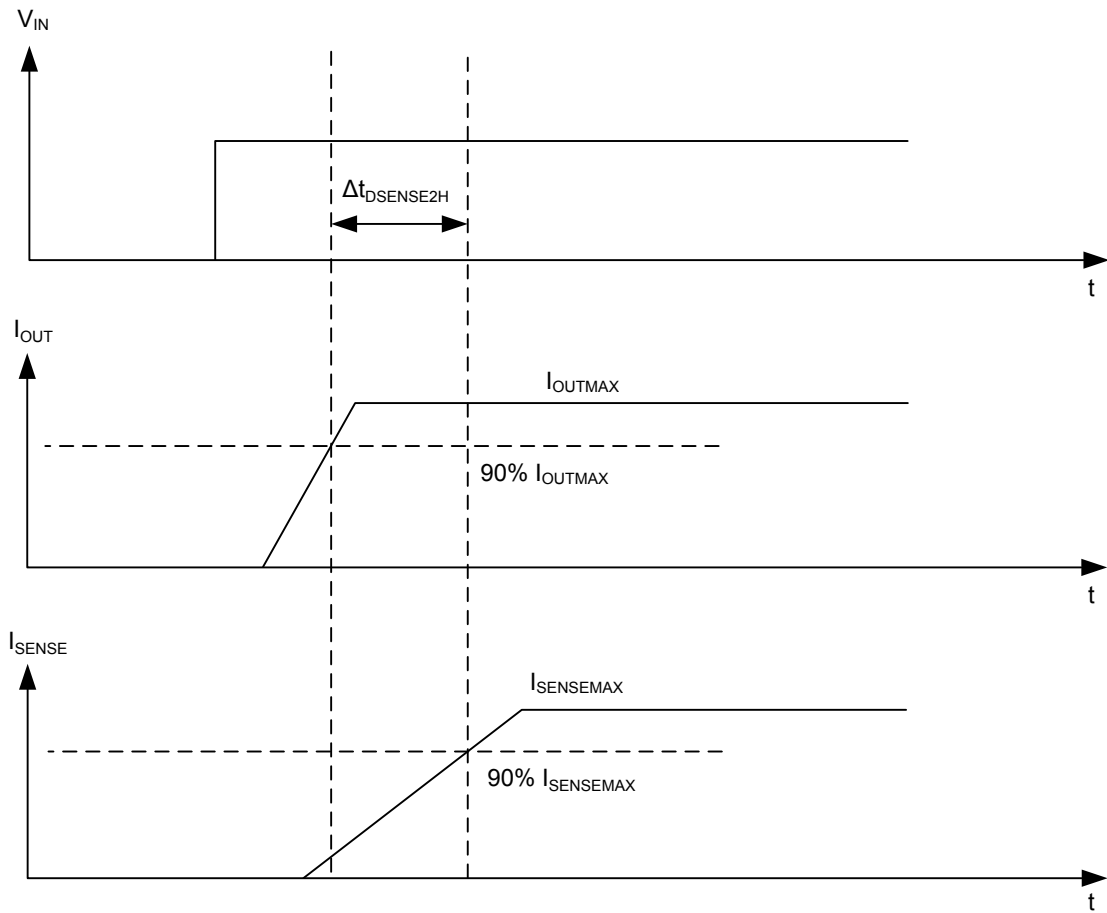
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Figure 9. Output stuck to  $V_{CC}$  detection delay time at FR\_Stby activation



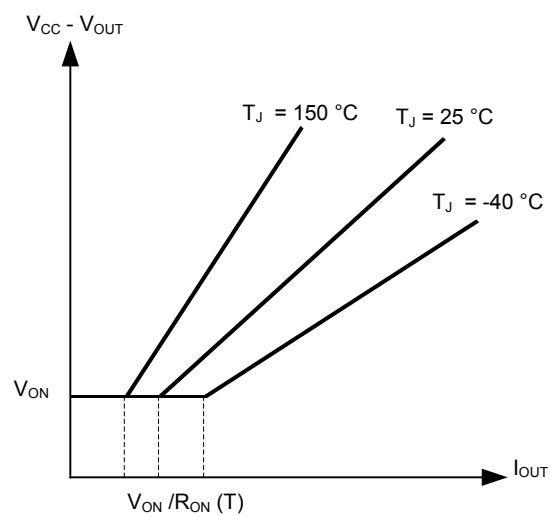
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Figure 10. Delay response time between rising edge of output current and rising edge of current sense

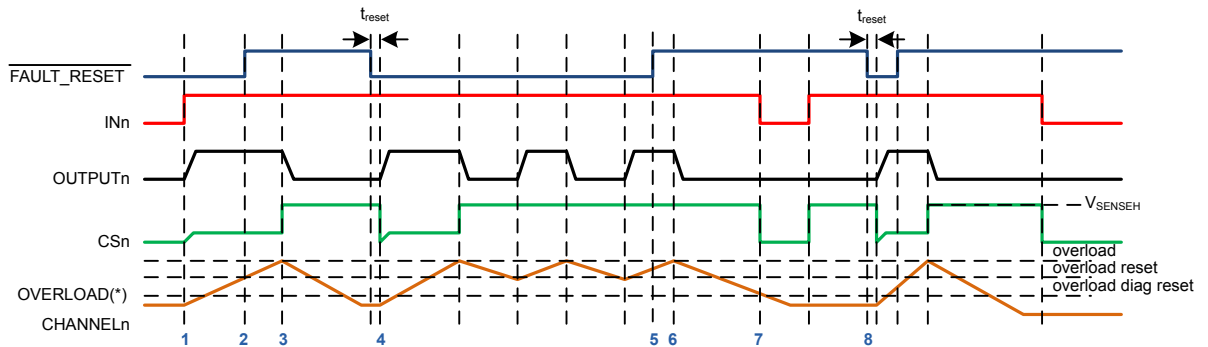


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Figure 11. Output voltage drop limitation



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**Figure 12. Device behavior in overload condition**


- 1: OUTPUTn and CSn controlled by INn
- 2: FAULT\_RESET from '0' to '1' → no action on CSn pin
- 3: overload latch-off. INn high → CSn high
- 4: FAULT\_RESET low AND Temp channeln < overload\_reset → overload latch reset after t\_reset
- 4 to 5: FAULT\_RESET low AND INn high → thermal cycling, CSn high
- 5: FAULT\_RESET high → latch-off reset disabled
- 6 to 7: overload event and FAULT\_RESET high → latch-off, no thermal cycling
- 7 to 8: overload diagnostic disabled/enabled by the input
- 8: overload latch-off reset by FAULT\_RESET

(\*) OVERLOAD = thermal shutdown OR power limitation

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**Table 11. Truth table**

Conditions	Fault reset standby	Input	Output	Sense
Standby	L	L	L	0
Normal operation	X	L	L	0
	X	H	H	Nominal
Overload	X	L	L	0
	X	H	H	> Nominal
Overtemperature/short to ground	X	L	L	0
	L	H	Cycling	V <sub>SENSEH</sub>
	H	H	Latched	V <sub>SENSEH</sub>
Undervoltage	X	X	L	0
Short to V <sub>BAT</sub>	L	L	H	0
	H	L	H	V <sub>SENSEH</sub>
	X	H	H	< Nominal
Openload off-state (with pull-up)	L	L	H	0
	H	L	H	V <sub>SENSEH</sub>
	X	H	H	0
Negative output voltage clamp	X	L	Negative	0

**Table 12. Electrical transient requirements (part 1)**

ISO 7637-2: 2004 (E) Test pulse	Test levels <sup>(1)</sup>		Number of pulses or test times	Burst cycle/pulse repetition time		Delays and impedence
	III	IV				
1	-450 V	-600 V	5000 pulses	0.5 s	5 s	1 ms, 50 Ω
2a	37 V	50 V	5000 pulses	0.2 s	5 s	50 μs, 2 Ω
3a	- 150 V	- 200 V	1 h	90 ms	100 ms	0.1 μs, 50 Ω
3b	+ 150 V	+ 200 V	1 h	90 ms	100 ms	0.1 μs, 50 Ω
4	- 12 V	- 16 V	1 pulse			100 ms, 0.01 Ω
5b <sup>(2)</sup>	+ 123 V	+ 174 V	1 pulse			350 ms, 1 Ω

1. The above test levels must be considered referred to  $V_{CC} = 24.5$  V except for pulse 5b.
2. Valid in case of external load dump clamp: 58 V maximum referred to ground.

**Table 13. Electrical transient requirements (part 2)**

ISO 7637-2: 2004 (E) Test pulse	Test level results <sup>(1)</sup>	
	III	IV
1	C	C
2a	C	C
3a	C	C
3b <sup>(2)</sup>	E	E
3b <sup>(3)</sup>	C	C
4	C	C
5b <sup>(4)</sup>	C	C

1. In order to guarantee the ISO transient classes a minimum 10 kΩ protection resistors are needed on logic pins.
2. Without capacitor between  $V_{CC}$  and GND.
3. With 10 nF between  $V_{CC}$  and GND.
4. External load dump clamp, 58 V maximum, referred to ground.

**Table 14. Electrical transient requirements (part 3)**

Class	Contents
C	All functions of the device are performed as designed after exposure to disturbance.
E	One or more functions of the device are not performed as designed after exposure to disturbance and cannot be returned to proper operation without replacing the device.

## 2.4 Electrical characteristics (curves)

Figure 13. Off-state output current

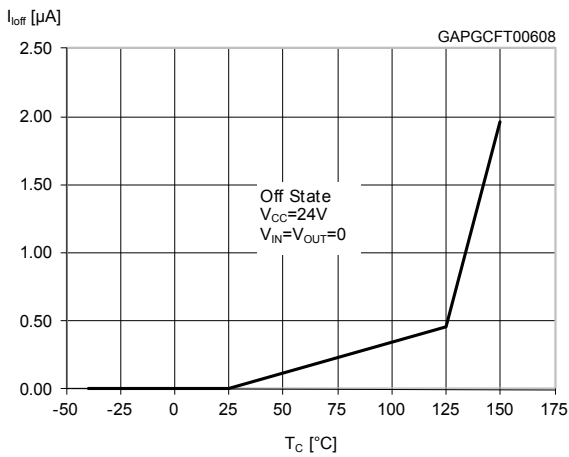


Figure 14. High level input current

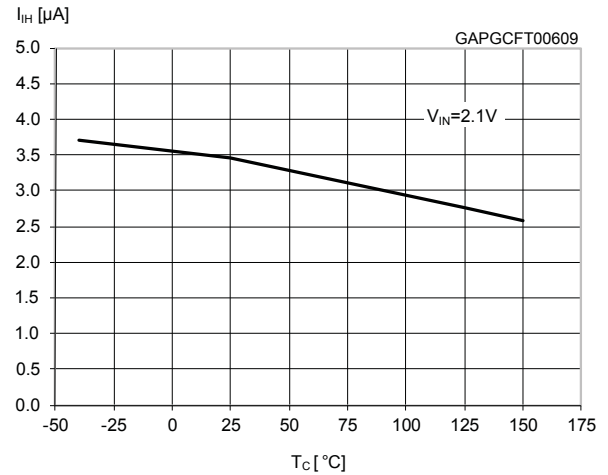


Figure 15. Input clamp voltage

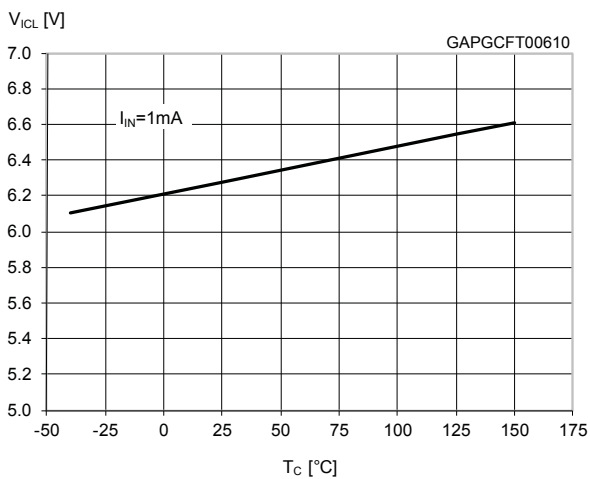


Figure 16. Low level input voltage

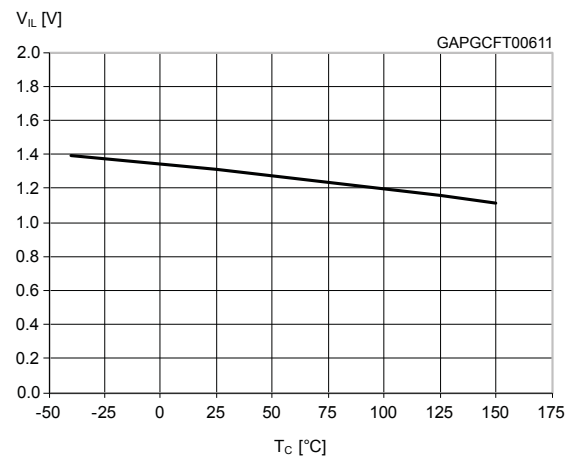


Figure 17. High level input voltage

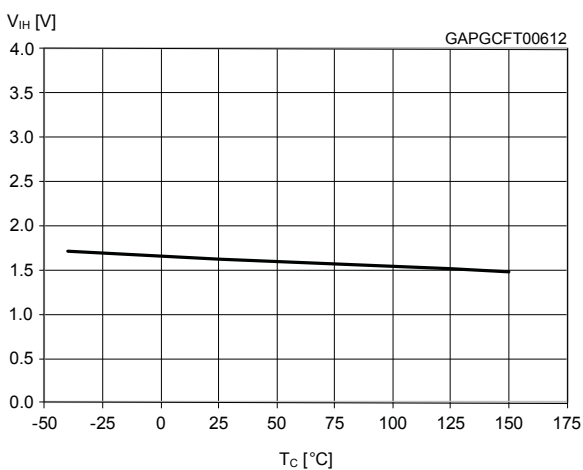


Figure 18. Input hysteresis voltage

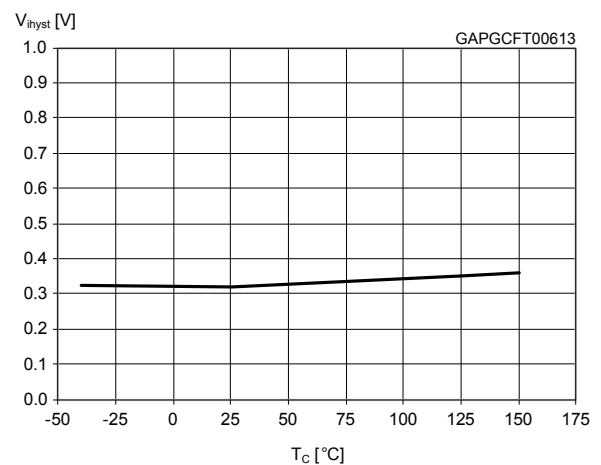


Figure 19. On-state resistance vs  $T_c$

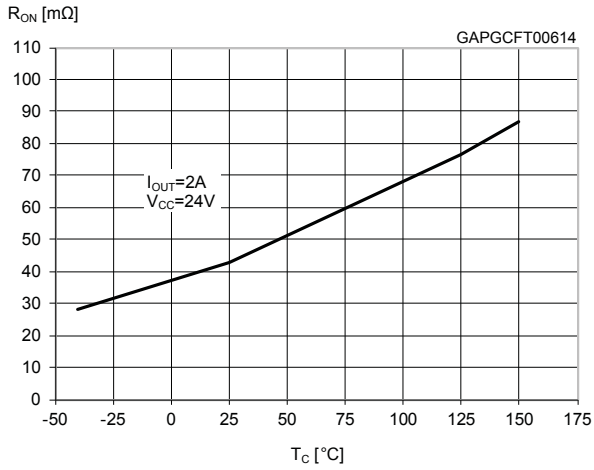


Figure 20. On-state resistance vs  $V_{CC}$

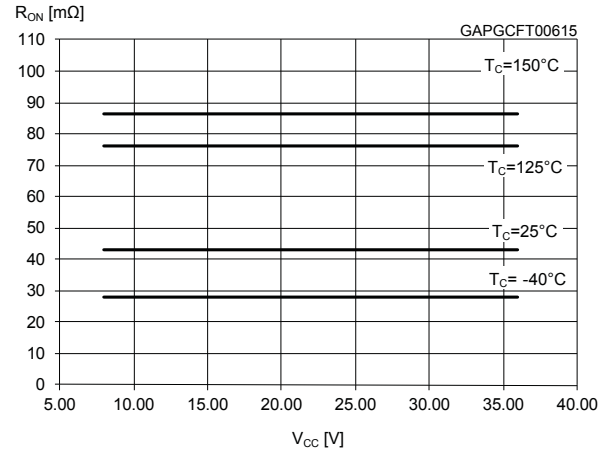


Figure 21. Turn-on voltage slope

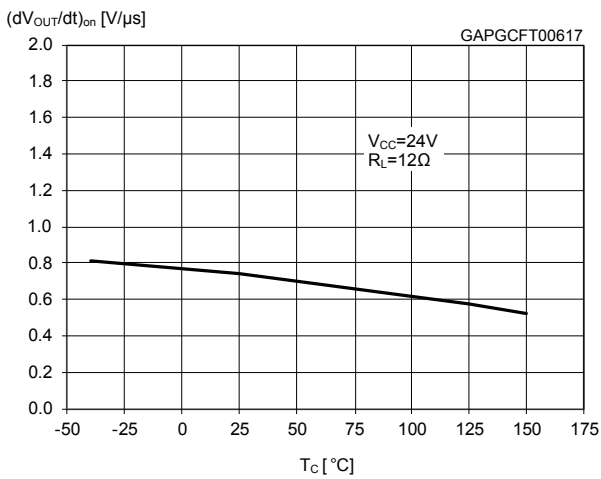


Figure 22. Turn-off voltage slope

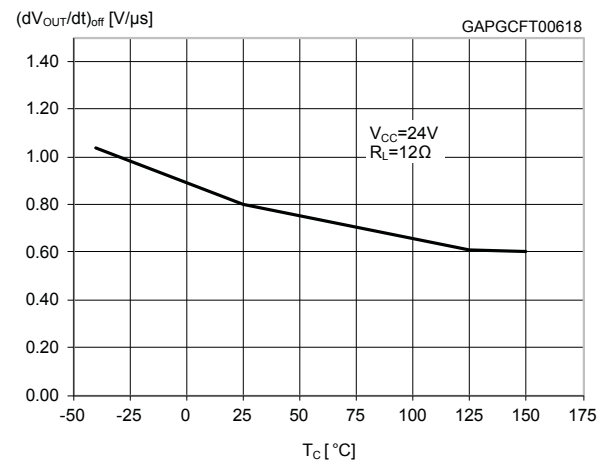
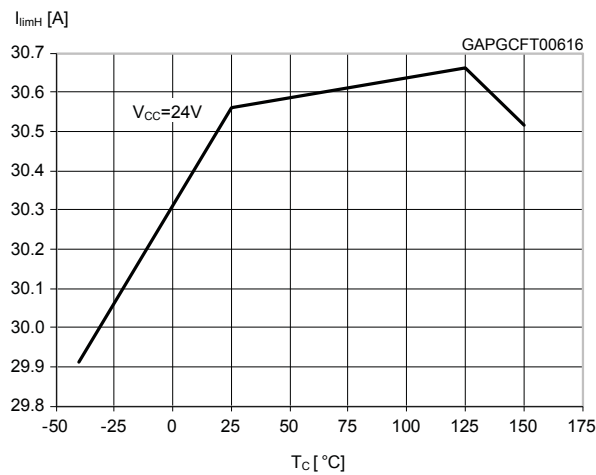
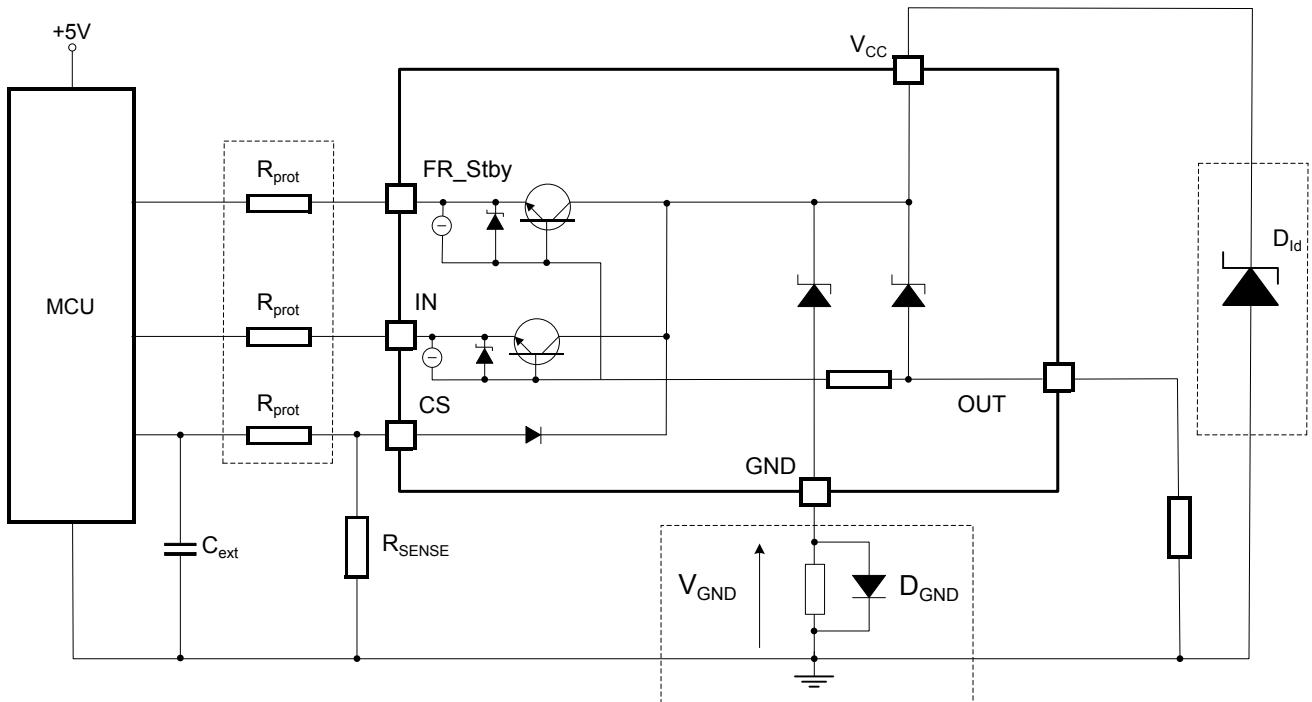


Figure 23.  $I_{LIMH}$  vs  $T_c$





### 3 Application information

**Figure 24. Application schematic**


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## 3.1 GND protection network against reverse battery

### 3.1.1 Solution 1: resistor in the ground line ( $R_{GND}$ only)

This solution can be used with any load type.

The following is an indication on how to dimension the  $R_{GND}$  resistor.

1.  $R_{GND} \leq 600 \text{ mV} / (I_{S(on)max.})$
2.  $R_{GND} \geq (-V_{CC}) / (-I_{GND})$

Where  $-I_{GND}$  is the DC reverse ground pin current and can be found in the absolute maximum rating section of the device datasheet.

Power dissipation in  $R_{GND}$  (when  $V_{CC} < 0 \text{ V}$ : during reverse battery situations) is:

$$P_D = (-V_{CC})^2 / R_{GND}$$

This resistor can be shared among several different HSDs. Please note that the value of this resistor should be calculated with formula (1) where  $I_{S(on)max.}$  becomes the sum of the maximum on-state currents of the different devices.

Please note that if the microprocessor ground is not shared by the device ground then the  $R_{GND}$  produces a shift ( $I_{S(on)max.} * R_{GND}$ ) in the input thresholds and the status output values. This shift varies depending on how many devices are ON in the case of several high side drivers sharing the same  $R_{GND}$ .

If the calculated power dissipation leads to a large resistor or several devices have to share the same resistor, then ST suggests solution 2 is used (see below).

### 3.1.2 Solution 2: diode ( $D_{GND}$ ) in the ground line

A resistor ( $R_{GND} = 4.7 \text{ k}\Omega$ ) should be inserted in parallel to  $D_{GND}$  if the device drives an inductive load.

This small signal diode can be safely shared amongst several different HSDs. Also in this case, the presence of the ground network produces a shift ( $\approx 600 \text{ mV}$ ) in the input threshold and in the status output values, if the microprocessor ground is not common to the device ground. This shift does not vary if more than one HSD shares the same diode/resistor network.

## 3.2 Load dump protection

$D_{ld}$  is necessary (voltage transient suppressor) if the load dump peak voltage exceeds the  $V_{CC}$  maximum DC rating. The same applies if the device is subject to transients on the  $V_{CC}$  line that are greater than the ones shown in the ISO 7637-2 2004 (E) [Table 12](#), [Table 13](#) and [Table 14](#).

## 3.3 MCU I/Os protection

If a ground protection network is used and negative transient is present on the  $V_{CC}$  line, the control pins are pulled negative. ST suggests that a resistor ( $R_{prot}$ ) has to be inserted in line to prevent the microcontroller I/Os pins from latching-up.

The value of these resistors is a compromise between the leakage current of the microcontroller and the current required by the HSD I/Os (Input levels compatibility) with the latch-up limit of microcontroller I/Os.

### Equation: $R_{prot}$ range calculation

$$-V_{CCpeak}/I_{latchup} \leq R_{prot} \leq (V_{OH\mu C} - V_{IH} - V_{GND}) / I_{IHmax}$$

### Calculation example:

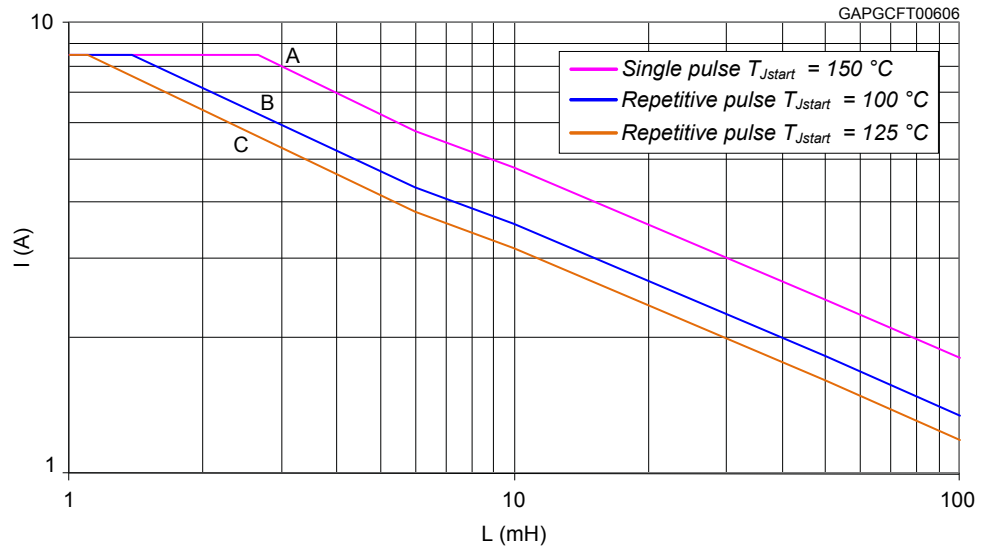
For  $V_{CCpeak} = -600 \text{ V}$  and  $I_{latchup} \geq 20 \text{ mA}$ ;  $V_{OH\mu C} \geq 4.5 \text{ V}$

$$30 \text{ k}\Omega \leq R_{prot} \leq 180 \text{ k}\Omega.$$

Recommended value:  $R_{prot} = 60 \text{ k}\Omega$ .

## 4 Maximum demagnetization energy (V<sub>CC</sub> = 24 V)

Figure 25. Maximum turn off current versus inductance

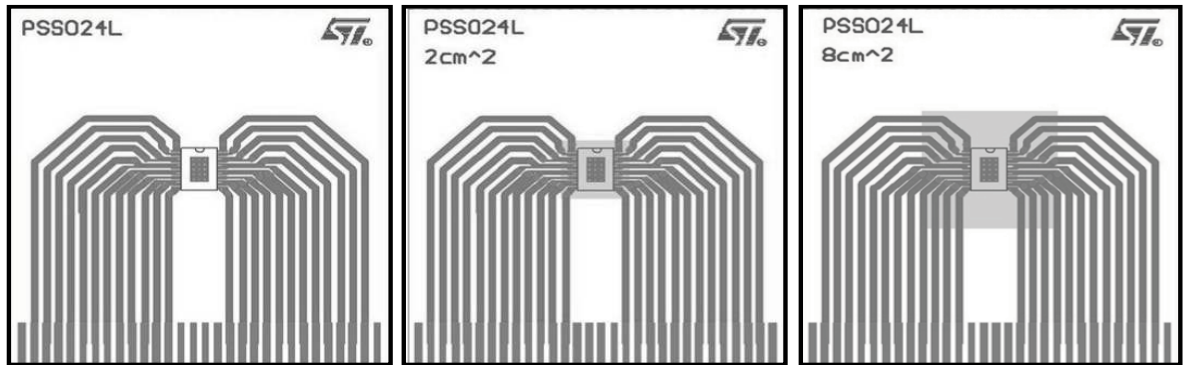


Note: Values are generated with  $R_L = 0 \Omega$ . In case of repetitive pulses,  $T_{Jstart}$  (at the beginning of each demagnetization) of every pulse must not exceed the temperature specified above for curves A and B.

## 5 Package and PCB thermal data

### 5.1 PowerSSO-24 thermal data

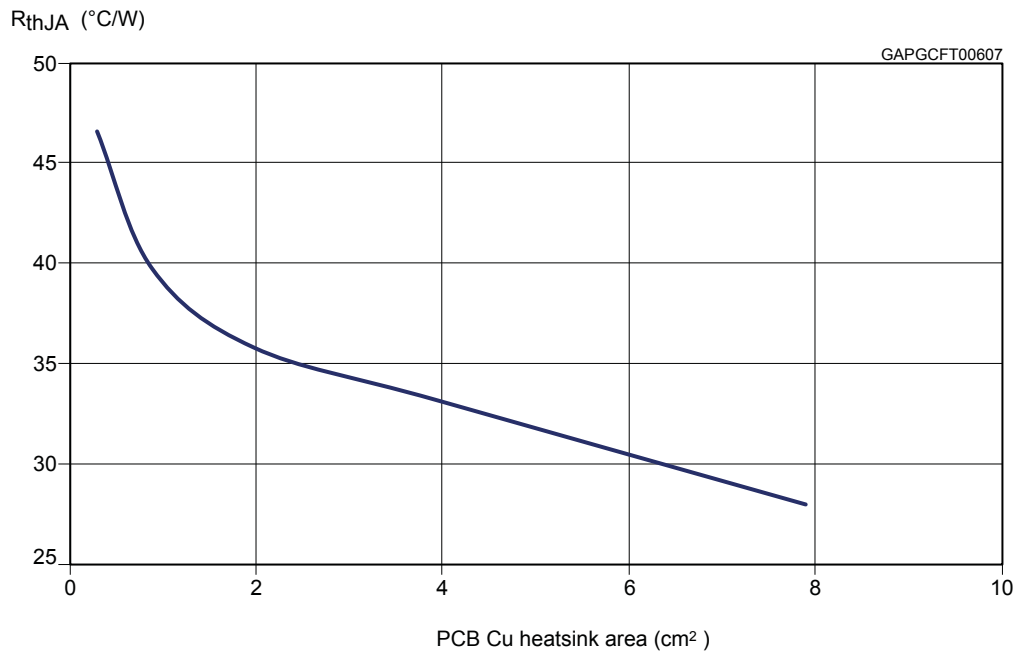
Figure 26. PowerSSO-24 PCB



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Layout condition of  $R_{th}$  and  $Z_{th}$  measurements (PCB: double layer, thermal vias, FR4 area = 77 mm x 86 mm, PCB thickness = 1.6 mm, Cu thickness = 70  $\mu\text{m}$  (front and back side), copper areas: from minimum pad lay-out to 8  $\text{cm}^2$ ).

Figure 27.  $R_{thJA}$  vs PCB copper area in open box free air condition (one channel ON)



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Figure 28. PowerSSO-24 thermal impedance junction ambient single pulse (one channel ON)

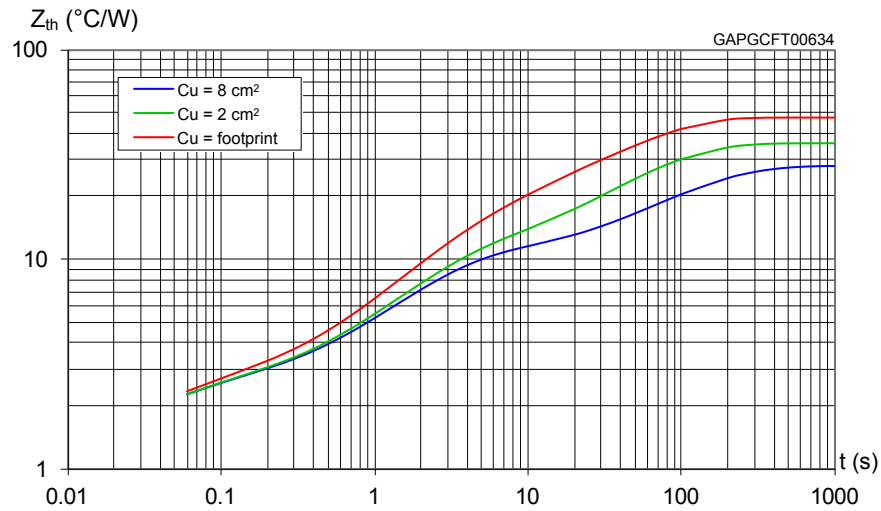
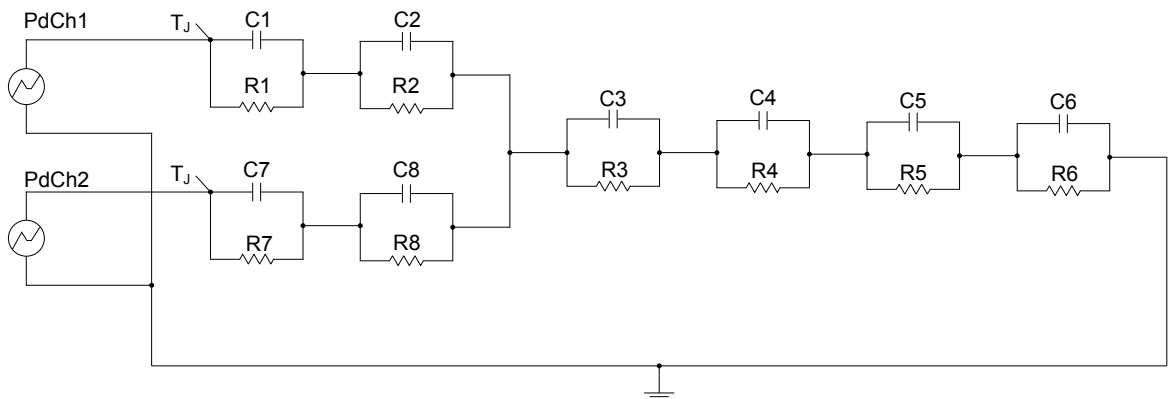


Figure 29. Thermal fitting model of a double channel HSD in PowerSSO-24



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The fitting model is a simplified thermal tool and is valid for transient evolutions where the embedded protections (power limitation or thermal cycling during thermal shutdown) are not triggered.

**Equation: pulse calculation formula**

$$Z_{th\delta} = R_{th} \cdot \delta + Z_{thp} (1 - \delta)$$

where  $\delta = t_p/T$

**Table 15. Thermal parameters**

Area/island (cm <sup>2</sup> )	Footprint	2	8
R1 = R7 (°C/W)	0.6		
R2 = R8 (°C/W)	0.75		
R3 (°C/W)	1		
R4 (°C/W)	7.7		
R5 (°C/W)	9	9	8
R6 (°C/W)	28	17	10
C1 = C7 (W.s/°C)	0.005		
C2 = C8 (W.s/°C)	0.01		
C3 (W.s/°C)	0.05		
C4 (W.s/°C)	0.3		
C5 (W.s/°C)	1	4	9
C6 (W.s/°C)	2.2	5	17



**Table 16. PowerSSO-24 mechanical data**

Symbol	Millimeters		
	Min.	Typ.	Max.
$\theta$	0°		8°
$\theta 1$	5°		10°
$\theta 2$	0°		
A			2.45
A1	0.00		0.10
A2	2.15		2.35
b	0.33		0.51
b1	0.28	0.40	0.48
c	0.23		0.32
c1	0.20	0.20	0.30
D	10.30 BSC		
D1	6.50		7.10
D2		3.65	
D3		4.30	
e	0.80 BSC		
E	10.30 BSC		
E1	7.50 BSC		
E2	4.10		4.70
E3		2.30	
E4		2.90	
G1		1.20	
G2		1.00	
G3		0.80	
h	0.30		0.40
L	0.55	0.70	0.85
L1	1.40 REF		
L2	0.25 BSC		
N	24		
R	0.30		
R1	0.20		
S	0.25		

**Table 17. PowerSSO-24 tolerance of form and position**

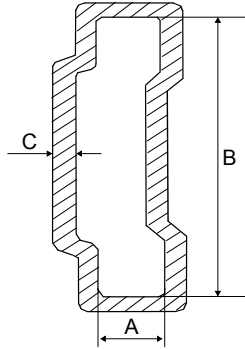
Symbol	Millimeters
aaa	0.20
bbb	0.20
ccc	0.10
ddd	0.20



Symbol	Millimeters
eee	0.10
fff	0.20
ggg	0.15

## 6.2 PowerSSO-24 packing information

Figure 31. PowerSSO-24 tube shipment (no suffix)

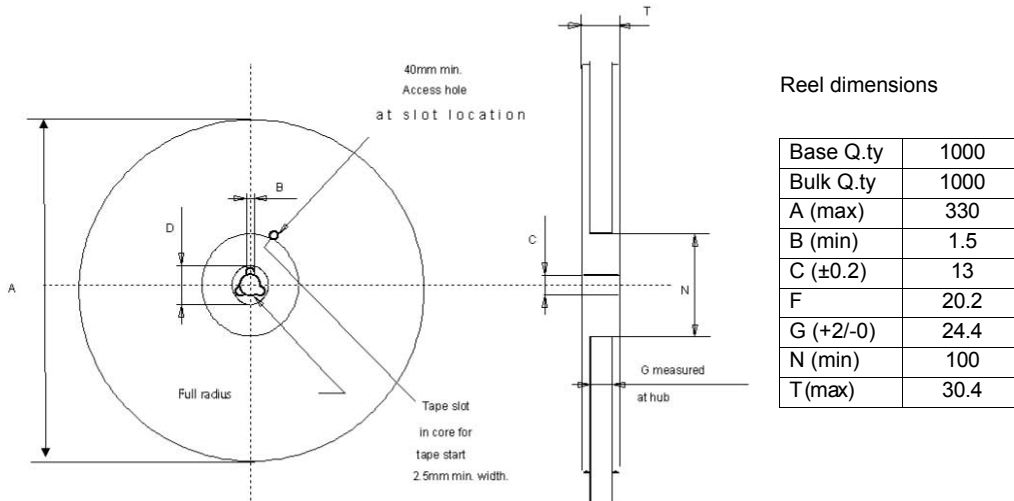


Base Q.ty	49
Bulk Q.ty	1225
Tube length ( $\pm 0.5$ )	532
A	3.5
B	13.8
C ( $\pm 0.1$ )	0.6

All dimensions are in mm.

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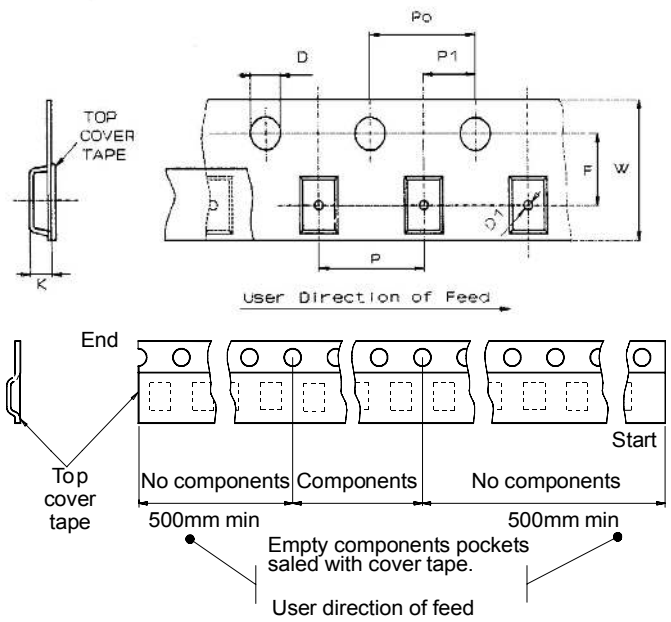
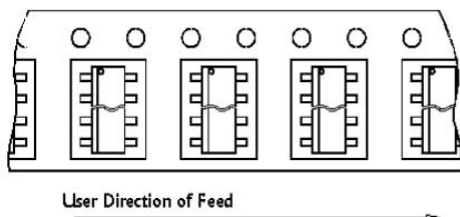
Figure 32. PowerSSO-24 tape and reel shipment (suffix "TR")



Tape dimension  
According to Electronic Industries Association (EIA) Standard 481 rev. A, Feb 1986

Tape width	W	24
Tape hole spacing	P0 ( $\pm 0.1$ )	4
Component spacing	P	12
Hole diameter	D ( $\pm 0.05$ )	1.55
Hole diameter	D1 (min)	1.5
Hole position	F ( $\pm 0.1$ )	11.5
Compartment depth	K(max)	2.85
Hole spacing	P1 ( $\pm 0.1$ )	2

All dimensions are in mm.



GAPGCT00421

## Revision history

**Table 18. Document revision history**

Date	Revision	Changes
07-Feb-2012	1	Initial release.
30-Mar-2012	2	Updated <i>Table 2: Suggested connections for unused and not connected pins.</i> <i>Table 9: Current sense (8 V &lt; V<sub>CC</sub> &lt; 36 V):</i> – dK <sub>0</sub> /K <sub>0</sub> : updated test condition from I <sub>OUT</sub> = 100 A to I <sub>OUT</sub> = 100 mA <i>Table 13: Electrical transient requirements (part 2):</i> – added note
18-Sep-2013	3	Updated Disclaimer.
24-Feb-2016	4	<i>Table 4: Thermal data:</i> – R <sub>thj-case</sub> : updated value Updated <i>Section 5.1: PowerSSO-24 mechanical data</i>
17-May-2022	5	Updated PowerSSO-24 cover image Updated <i>Table 5. Power section.</i> Updated notes in <i>Table 12. Electrical transient requirements (part 1)</i> Moved <i>Section 3.4: Maximum demagnetization energy (V<sub>CC</sub> = 24 V)</i> to <i>Section 4 Maximum demagnetization energy (V<sub>CC</sub> = 24 V)</i> Updated <i>Section 6.1 PowerSSO-24 package information.</i> Minor text changes.

## Contents

<b>1</b>	<b>Block diagram and pin description</b>	<b>3</b>
<b>2</b>	<b>Electrical specification</b>	<b>5</b>
2.1	Absolute maximum ratings	5
2.2	Thermal data	6
2.3	Electrical characteristics	6
2.4	Electrical characteristics (curves)	15
<b>3</b>	<b>Application information</b>	<b>17</b>
3.1	GND protection network against reverse battery	17
3.1.1	Solution 1: resistor in the ground line (R <sub>GND</sub> only)	17
3.1.2	Solution 2: diode (D <sub>GND</sub> ) in the ground line	18
3.2	Load dump protection	18
3.3	MCU I/Os protection	18
<b>4</b>	<b>Maximum demagnetization energy (V<sub>CC</sub> = 24 V)</b>	<b>19</b>
<b>5</b>	<b>Package and PCB thermal data</b>	<b>20</b>
5.1	PowerSSO-24 thermal data	20
<b>6</b>	<b>Package information</b>	<b>23</b>
6.1	PowerSSO-24 package information	23
6.2	PowerSSO-24 packing information	26
	<b>Revision history</b>	<b>27</b>

## List of tables

<b>Table 1.</b>	Pin function . . . . .	3
<b>Table 2.</b>	Suggested connections for unused and not connected pins . . . . .	4
<b>Table 3.</b>	Absolute maximum ratings . . . . .	5
<b>Table 4.</b>	Thermal data . . . . .	6
<b>Table 5.</b>	Power section . . . . .	6
<b>Table 6.</b>	Switching ( $V_{CC} = 24\text{ V}$ , $T_J = 25\text{ °C}$ ) . . . . .	7
<b>Table 7.</b>	Logic inputs . . . . .	7
<b>Table 8.</b>	Protections and diagnostics . . . . .	8
<b>Table 9.</b>	Current sense ( $8\text{ V} < V_{CC} < 36\text{ V}$ ) . . . . .	9
<b>Table 10.</b>	Openload detection ( $V_{FR\_Stby} = 5\text{ V}$ ) . . . . .	10
<b>Table 11.</b>	Truth table . . . . .	13
<b>Table 12.</b>	Electrical transient requirements (part 1) . . . . .	14
<b>Table 13.</b>	Electrical transient requirements (part 2) . . . . .	14
<b>Table 14.</b>	Electrical transient requirements (part 3) . . . . .	14
<b>Table 15.</b>	Thermal parameters . . . . .	22
<b>Table 16.</b>	PowerSSO-24 mechanical data . . . . .	24
<b>Table 17.</b>	PowerSSO-24 tolerance of form and position . . . . .	24
<b>Table 18.</b>	Document revision history . . . . .	27

## List of figures

<b>Figure 1.</b>	Block diagram . . . . .	3
<b>Figure 2.</b>	Configuration diagram PowerSSO-24 (top view) . . . . .	4
<b>Figure 3.</b>	Current and voltage conventions . . . . .	5
<b>Figure 4.</b>	$t_{\text{reset}}$ definition . . . . .	8
<b>Figure 5.</b>	$t_{\text{stby}}$ definition . . . . .	8
<b>Figure 6.</b>	Current sense delay characteristics . . . . .	10
<b>Figure 7.</b>	Openload off-state delay timing . . . . .	10
<b>Figure 8.</b>	Switching characteristics . . . . .	11
<b>Figure 9.</b>	Output stuck to $V_{\text{CC}}$ detection delay time at FR_Stby activation . . . . .	11
<b>Figure 10.</b>	Delay response time between rising edge of output current and rising edge of current sense . . . . .	12
<b>Figure 11.</b>	Output voltage drop limitation . . . . .	12
<b>Figure 12.</b>	Device behavior in overload condition . . . . .	13
<b>Figure 13.</b>	Off-state output current . . . . .	15
<b>Figure 14.</b>	High level input current . . . . .	15
<b>Figure 15.</b>	Input clamp voltage . . . . .	15
<b>Figure 16.</b>	Low level input voltage . . . . .	15
<b>Figure 17.</b>	High level input voltage . . . . .	15
<b>Figure 18.</b>	Input hysteresis voltage . . . . .	15
<b>Figure 19.</b>	On-state resistance vs $T_{\text{C}}$ . . . . .	16
<b>Figure 20.</b>	On-state resistance vs $V_{\text{CC}}$ . . . . .	16
<b>Figure 21.</b>	Turn-on voltage slope . . . . .	16
<b>Figure 22.</b>	Turn-off voltage slope . . . . .	16
<b>Figure 23.</b>	$I_{\text{LIMH}}$ vs $T_{\text{C}}$ . . . . .	16
<b>Figure 24.</b>	Application schematic . . . . .	17
<b>Figure 25.</b>	Maximum turn off current versus inductance . . . . .	19
<b>Figure 26.</b>	PowerSSO-24 PCB . . . . .	20
<b>Figure 27.</b>	$R_{\text{thJA}}$ vs PCB copper area in open box free air condition (one channel ON) . . . . .	20
<b>Figure 28.</b>	PowerSSO-24 thermal impedance junction ambient single pulse (one channel ON) . . . . .	21
<b>Figure 29.</b>	Thermal fitting model of a double channel HSD in PowerSSO-24 . . . . .	21
<b>Figure 30.</b>	PowerSSO-24 package dimensions . . . . .	23
<b>Figure 31.</b>	PowerSSO-24 tube shipment (no suffix) . . . . .	26
<b>Figure 32.</b>	PowerSSO-24 tape and reel shipment (suffix "TR") . . . . .	26

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